

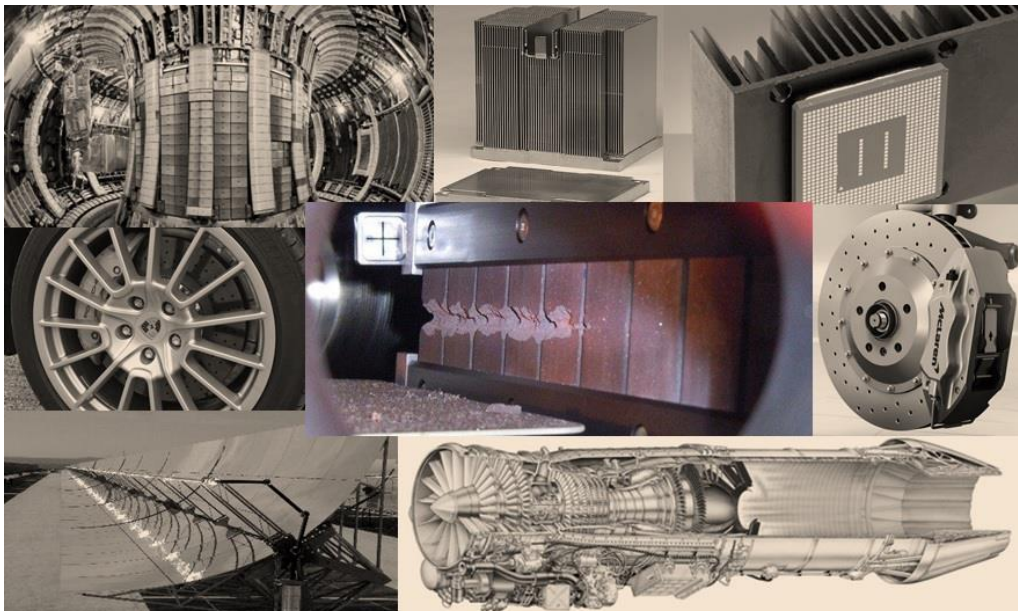
# Applications of Thermal Management Materials

## EuCARD<sup>2</sup> meets Industry Workshop

6 November 2015, CERN, Geneva, Switzerland

In the framework of EuCARD<sup>2</sup>, an ambitious research program has been undertaken to investigate, manufacture and characterise novel composite materials. These are intended to combine optimum mechanical, thermal and electrical properties, such as mechanical strength, melting temperature, thermal shock resistance, electrical conductivity, and energy absorption.

These materials are of particular interest for thermal management applications such as high power density electronic packaging, aerospace, automotive, nuclear fusion and solar energy. This EuCARD<sup>2</sup> meets industry event aims to bring together experts in the research and industrial sector, to exchange ideas on the latest developments in design, manufacture, testing and applications of Thermal Management Materials.



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More information on the programme and registration can be found here:  
<http://indico.cern.ch/event/400452/overview>